

IN THE CLAIMS:

1. (Currently amended) A manufacturing method of a display device comprising:
forming a conductive film over a substrate by ejecting liquid droplets containing
conductive particles ~~on a film being processed~~ by using a first liquid droplet ejecting
apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet
ejecting nozzles arranged linearly to form a conductive film locally;
forming a resist pattern locally on the conductive film by using a second liquid droplet
ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of
liquid droplet ejecting nozzles arranged linearly; and
forming a wiring by etching the conductive film with the resist pattern as a mask at an
atmospheric pressure or a pressure close to the atmospheric pressure by using a plasma
generating means comprising [[a]] one pair of electrodes to form a wiring.

2. (Canceled) A manufacturing method of a display device according to claim 1,
wherein the conductive film is locally etched at an atmospheric pressure or a pressure close to
the atmospheric pressure by using a plasma generating means comprising one pair of
cylindrical electrodes or a plasma processing apparatus comprising a plasma generating
means provided with a plurality of pairs of cylindrical electrodes.

3. (Currently amended) A manufacturing method of a display device according to
claim 1, wherein after ~~etching the conductive film~~ forming the wiring, the resist film is
locally etched at an atmospheric pressure or a pressure close to the atmospheric pressure by
using the plasma generating means provided with [[a]] one pair of ~~cylindrical~~ electrodes ~~or~~
~~the plasma generating means provided with a plurality of pairs of cylindrical electrodes~~
~~arranged linearly.~~

4. (Currently amended) A manufacturing method of a display device comprising:

forming a conductive film ~~[[on]]over~~ a substrate ~~being processed by ejecting liquid droplets containing conductive particles by using a first liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly; and~~

after forming the conductive film, forming a wiring by etching an unnecessary portion of the conductive film locally by using a plasma generating means provided with ~~[[a]] one pair of cylindrical electrodes or a plasma generating means provided with a plurality of pairs of cylindrical electrodes arranged linearly~~ at an atmospheric pressure or a pressure close to the atmospheric pressure ~~to form a wiring.~~

5. (Currently amended) A manufacturing method of a display device comprising:

forming a conductive film ~~[[on]]over~~ a substrate ~~being processed by using a liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly; and~~

forming a resist pattern on the conductive film;

after forming the ~~conductive film~~ resist pattern, forming a wiring by etching an unnecessary portion of the conductive film locally by using a plasma generating ~~apparatus means~~ provided with ~~[[a]] one pair of cylindrical electrodes or a plasma generating means provided with a plurality of pairs of cylindrical electrodes arranged linearly~~ at an atmospheric pressure or a pressure close to the atmospheric pressure ~~to form a wiring.~~

6. (New) A manufacturing method of a display device according to claim 1, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

7. (New) A manufacturing method of a display device according to claim 4, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

8. (New) A manufacturing method of a display device according to claim 5, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

9. (New) A manufacturing method of a display device according to claim 5, wherein after forming the wiring, the resist film is etched at an atmospheric pressure or a pressure close to the atmospheric pressure by using the plasma generating means provided with one pair of electrodes.

10. (New) A manufacturing method of a display device according to claim 1, wherein the one pair of electrodes are cylindrical electrodes.

11. (New) A manufacturing method of a display device according to claim 4, wherein the one pair of electrodes are cylindrical electrodes.

12. (New) A manufacturing method of a display device according to claim 5, wherein the one pair of electrodes are cylindrical electrodes.